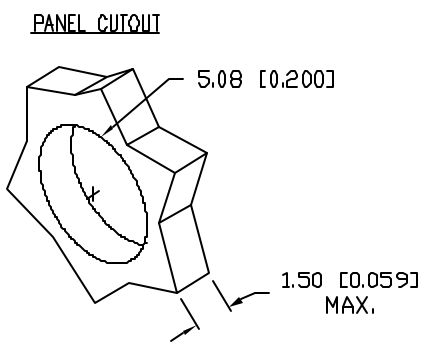
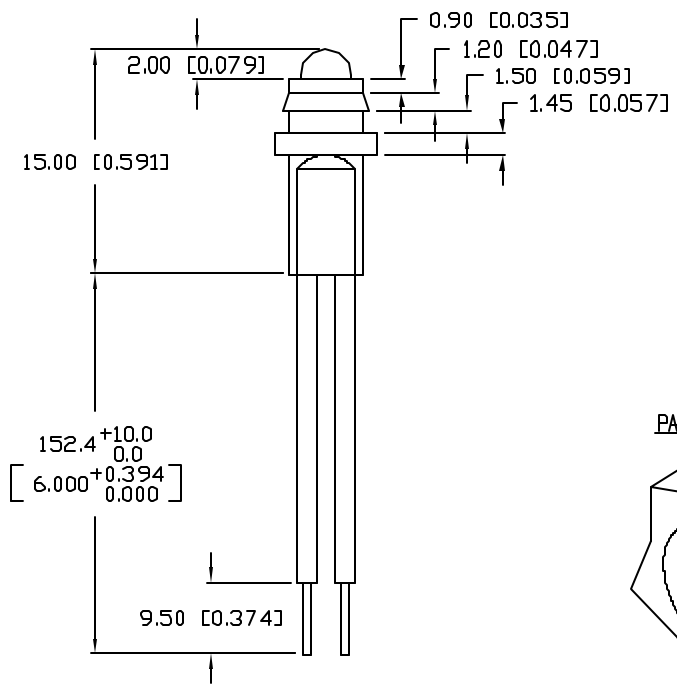
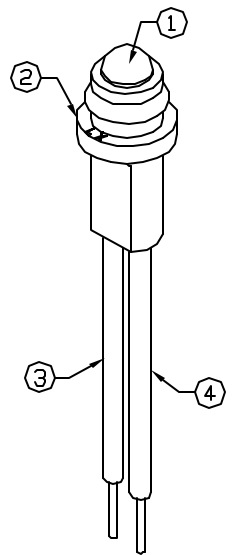
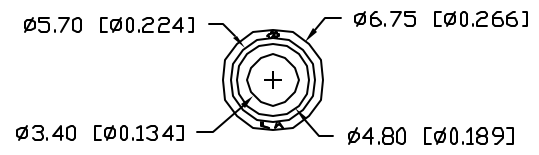


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PART NUMBER
SSI-RM3091SUGD-150

REV.
A

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #11317.	3.17.06



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		574		nm	
FORWARD VOLTAGE		2.2	2.6	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu\text{A}$
AXIAL INTENSITY		50		med	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM 25°C	-1.2	mW/ $^{\circ}\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^{\circ}\text{C}$

* $t < 10\mu\text{s}$

- NOTES:
- SSL-LX306F4SUGD, GREEN LED.
 - SSH-RM3091, BLACK RUBBER HOUSING.
 - ANODE LEAD: LXP-WST26RDT0C, 26 AWG STRANDED, RED INSULATION, CUT 160mm LONG, STRIP 2mm & 9.5mm.
 - CATHODE LEAD: LXP-WST26BLT0C, 26 AWG STRANDED, BLACK INSULATION, CUT 160mm LONG, STRIP 2mm & 9.5mm.
 - CRIMP OR SOLDER WIRE LEADS TO LED LEADS.

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*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030), MIN.=^{+DECIMAL PRECISION}-0.00, MAX.=^{+0.00}-DECIMAL PRECISION

REV.	PART NUMBER
A	SSI-RM3091SUGD-150

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T-3mm 574nm AlInGaP GREEN LED PANEL INDICATOR,
GREEN DIFFUSED LENS, 6" WIRE LEADS.

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: GT	CHECKED BY:	APPROVED BY:	DATE: 4.5.02
			PAGE: 1 OF 1
			SCALE: N/A